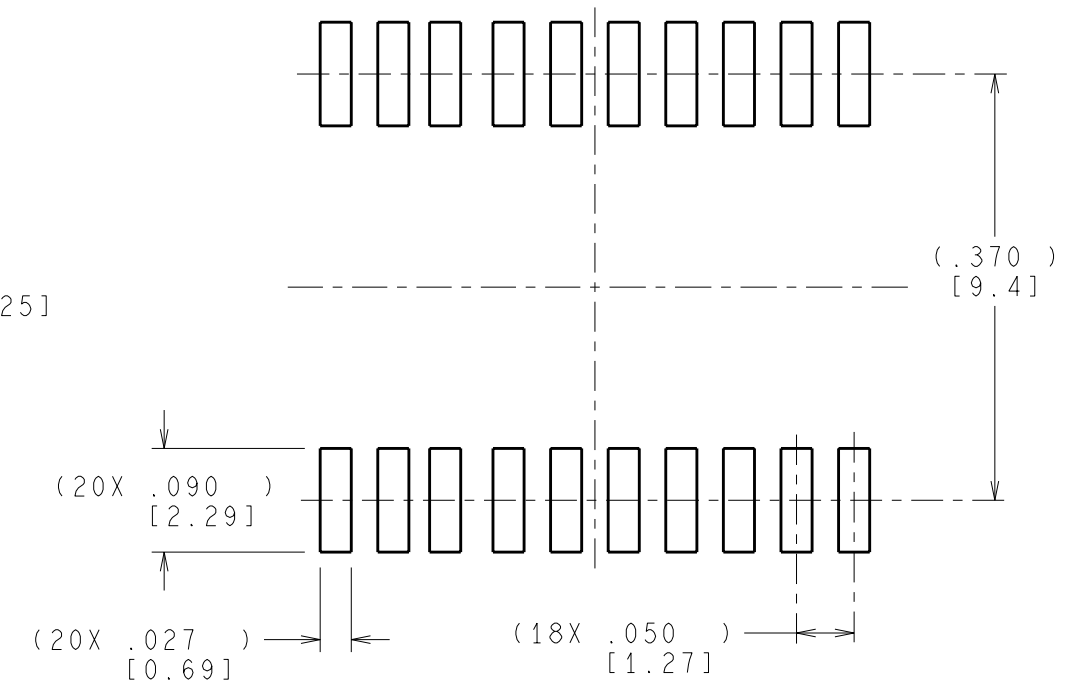
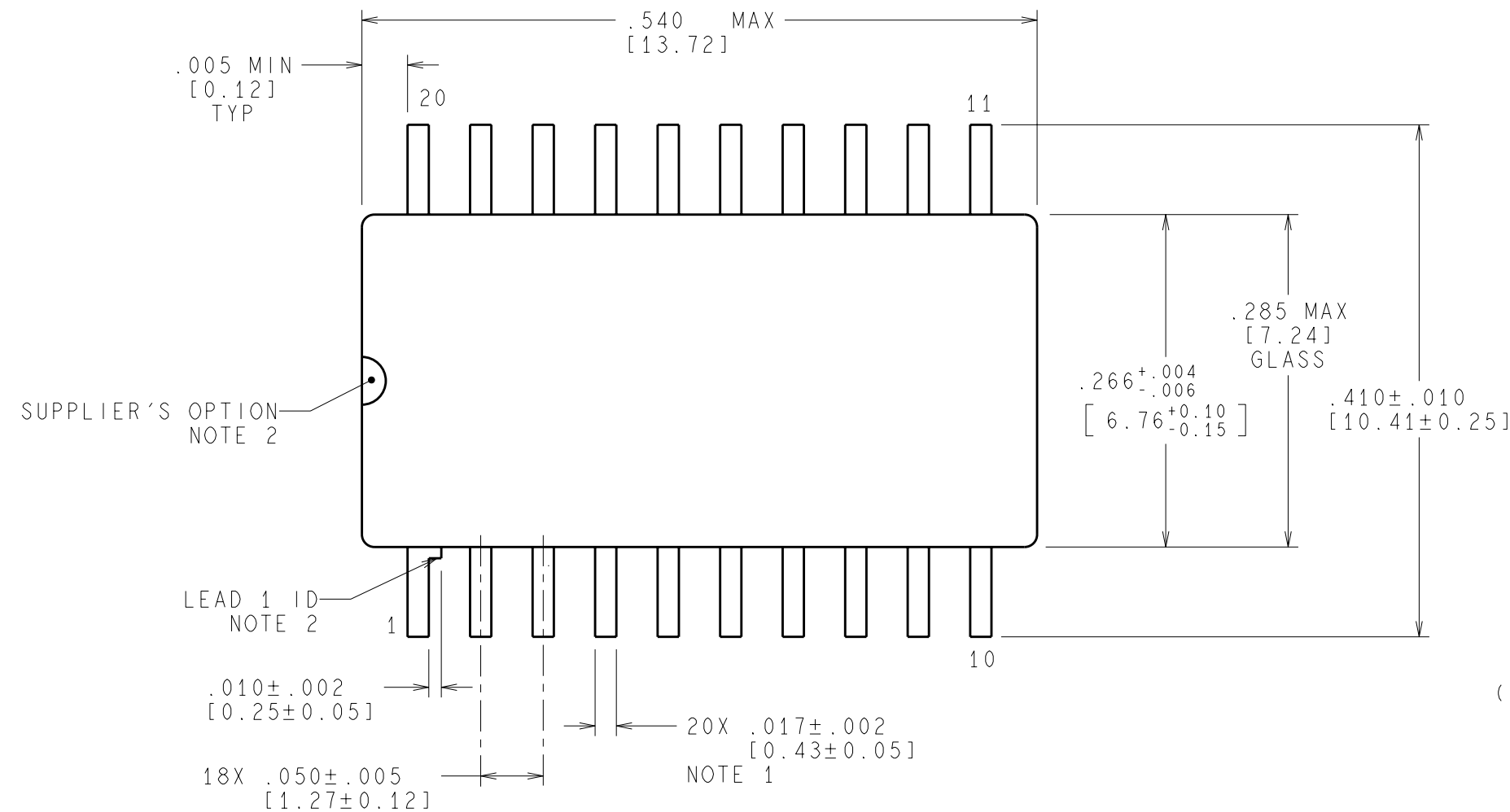
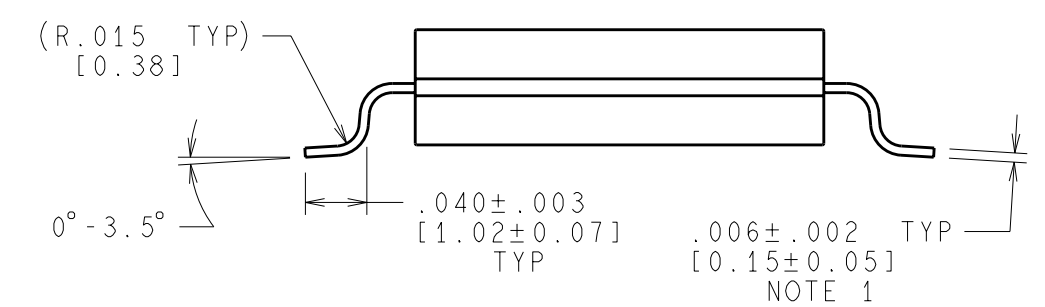
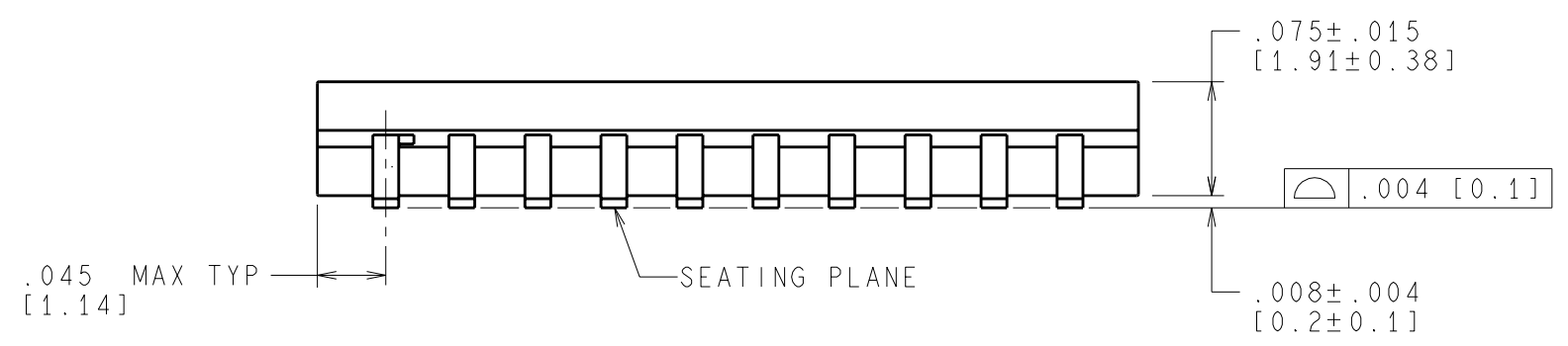


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11842	10/13/1997	TL/KH
B	DIM .410 WAS .391; UPDATE NOTE 3	12013	06/15/1998	MS/CD
C	ADD LAND PATTERN; REVISE TITLE PER STDS; UPDATE NOTE 3; CHANGE DWG FORMAT TO B SIZE	2366	07/26/2007	TL/JL
D	REVISE NOTE 1	2565	08/12/2008	TL/RW



RECOMMENDED LAND PATTERN



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- LEAD 1 IDENTIFICATION SHALL BE:
  - A NOTCH OR OTHER MARK WITHIN THIS AREA
  - A TAB ON LEAD 1, EITHER SIDE.
- NO JEDEC REGISTRATION AS OF AUGUST 2008.

CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS  
DIMENSIONS IN ( ) FOR REFERENCE ONLY

MIL-STD-1835D  
CONFIGURATION CONTROL

APPROVALS	DATE	National Semiconductor	
DRAWN T. LEQUANG	10/13/1997	2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DFTG. CHK. KURT SINCERBOX	08/12/2008	CERPACK, .540x.266x.075in, 20 LD, .050in PITCH, GULL WING	
ENGR. CHK. RANDY WALBERG	08/12/2008		
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	NTS	B	(SC)MKT-WG20A
FORMERLY: N/A	SHEET 1 of 1		REV D